

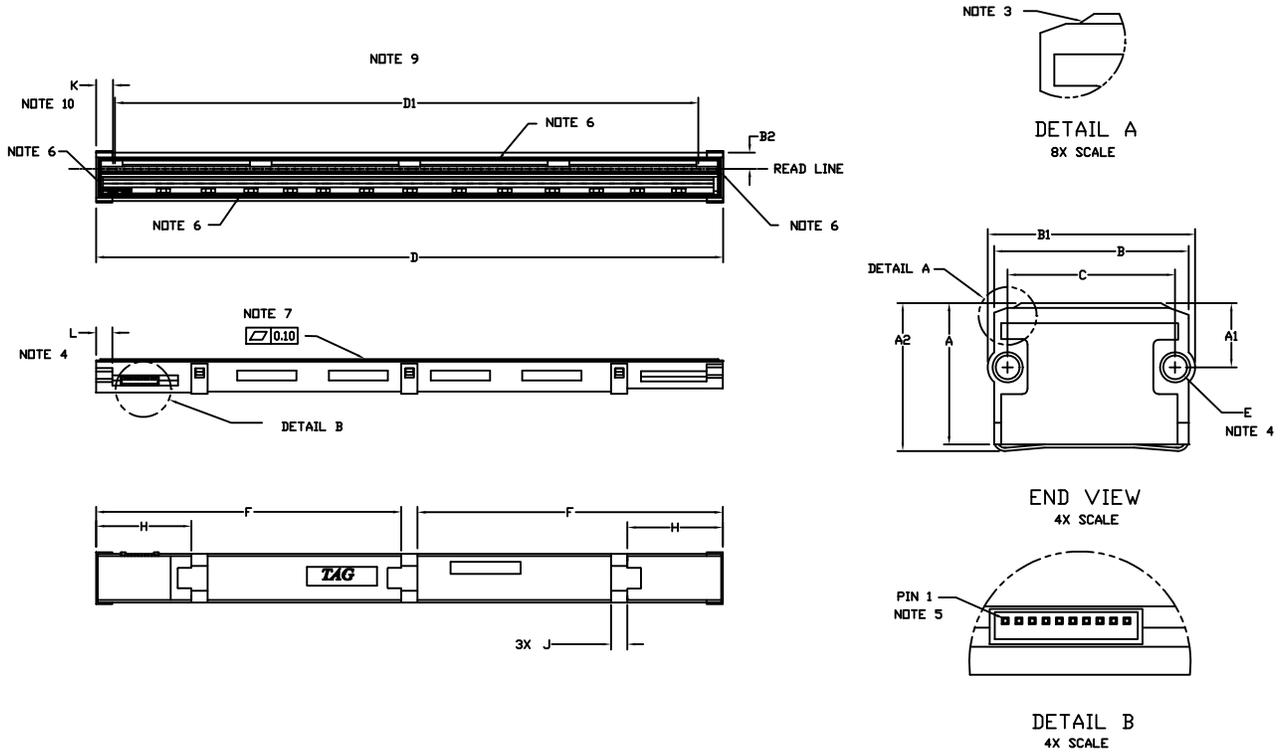
MECHANICAL CASE OUTLINE PACKAGE DIMENSIONS

ON Semiconductor®



IMAGE SENSOR MODULE CASE MODAC ISSUE A

DATE 11 MAY 2010



NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. LEADING EDGE OF THE APPROACH ANGLE ON THE GLASS IS LOWER THAN THE TOP OF THE HOUSING.
4. BORE DEPTH IS 6.0 WITH A 0.3 LEAD-IN CHAMFER.
5. PIN HEADER, MODEL NUMBER EBW-PK23-P010L2-3Z, 1X10 PIN, PITCH 1.25.
6. GLASS IS GLUED ON ALL 4 SIDES.
7. GLASS THICKNESS IS 1.85.
8. USE M2.3 SELF TAPPING SCREWS FOR MOUNTING. TORQUE SCREWS BETWEEN 1.80 KGF-CM AND 2.00 KGF-CM.
9. DIMENSION D1 DENOTES THE SCAN LENGTH.
10. DIMENSION K DENOTES THE POSITION OF THE FIRST PIXEL.

MILLIMETERS		
DIM	MIN	MAX
A	12.60	13.60
A1	5.45	6.45
A2	13.20	14.20
B	17.70	18.30
B1	18.90	19.50
B2	5.50	6.50
C	15.40	15.60
D	231.60	232.60
D1	216.00	REF
E	2.10	2.30
F	112.50	113.50
H	34.80	35.80
J	5.70	6.30
K	5.30	7.30
L	6.00	REF

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STATUS:	ON SEMICONDUCTOR STANDARD	
NEW STANDARD:		
DESCRIPTION:	IMAGE SENSOR MODULE	PAGE 1 OF 2

